

Listing of Claims:

1. (currently amended) A power semiconductor module for mounting on a flat body, comprising a plurality of partial modules, each of said partial modules having:

a base plate;

a framelike housing;

terminal elements for load terminals and auxiliary terminals;

at least one electrically insulated substrate disposed inside said housing on said base plate, said substrate having an insulation body with a plurality of metal connection tracks located therein and insulated from one another, and power semiconductor components, located on said connection tracks and electrically connected thereto;

at least two open-slotlike recesses on a side thereof, and positioned so that, when said partial modules are assembled into a power semiconductor module, said recesses in sides of adjacent partial modules face one another to form closed slots;
and

~~means~~ a cap for connecting adjacent partial modules to one another;

said cap having round slotlike recesses for receiving screws, which, in the abutting region of said partial modules, are aligned with said recesses that form said slots therein.

2. (canceled)

3. (currently amended) The power semiconductor module of claim ~~2~~ 1,
wherein

said cap is connected to said partial modules by means of snap-detent connections, said housing has detent lugs, and said cap has abutments formed to cooperate with said detent lugs.

4. - 5. (canceled)

6. (original) The power semiconductor module of claim 1, wherein
each of said partial modules has, on a first side adjacent to another partial module, at least one detent lug, and on a second, opposite, side thereof has at least one abutment adapted to cooperate with a detent lug in an adjacent partial module

7. (original) The power semiconductor module of claim 1, wherein
said means for connecting comprises fixing connections.

8. (original) The power semiconductor module of claim 7, wherein
said fixing connections include a snap-detent connection for connection of
a first partial module to an adjacent partial module.

9. (original) The power semiconductor module of claim 8, wherein
each of said partial modules has at least two open-slotlike recesses on a
side thereof, and positioned so that, when said partial modules are assembled into a

power semiconductor module, said recesses in said sides of adjoining partial modules face one another to form closed slots.

10. (original) The power semiconductor module of claim 7, wherein said fixing connections include a rail that covers all said recesses and said slots formed thereby in adjacent partial modules.